



SDI Review Form 1.6

Journal Name:	Journal of Engineering Research and Reports
Manuscript Number:	Ms_JERR_44923
Title of the Manuscript:	Improvement on Semiconductor Substrate Design with Package Modeling and Simulation for Mitigation of Delamination and Voids
Type of the Article	Original Research Article

General guideline for Peer Review process:

This journal's peer review policy states that **NO** manuscript should be rejected only on the basis of '**lack of Novelty**', provided the manuscript is scientifically robust and technically sound. To know the complete guideline for Peer Review process, reviewers are requested to visit this link:

(<http://www.sciencedomain.org/page.php?id=sdi-general-editorial-policy#Peer-Review-Guideline>)

PART 1: Review Comments

	Reviewer's comment	Author's comment (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)
Compulsory REVISION comments	Line 48 -52 – Die Attach Film (DAF), BGA (ball grid array), bond line thickness (BLT), dicing die attach film (DDAF) – Use one common method to provide acronyms. Do standardize. Line 56-61 - Reliability issue, delamination issue – Reference required. Line 78 - 20um . I believe it's supposed to be a μ. Also correct for Fig 6. Do check for the whole article. Line 196 – Fig 13 – Does the Non planarized exactly overlap planarized line?	Line 48-52 – Done Line 56-61 – Done Line 78 – Done Line 196 – For this case yes. But you can do selective planarized design, wherein some parts are non-planarized and other parts planarized.
Minor REVISION comments		
Optional/General comments		

PART 2:

	Reviewer's comment	Author's comment (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)
Are there ethical issues in this manuscript?	(If yes, Kindly please write down the ethical issues here in details)	